



SDM2A40CSP

2A SCHOTTKY BARRIER RECTIFIER CHIP SCALE PACKAGE

Product Summary

| V _{RRM} (V) | I _O (A) | V _{F Max} (V) | I _{R Max} (μΑ) |
|----------------------|--------------------|------------------------|-------------------------|
| 40 | 2 | 0.58 | 100 |

Features and Benefits

- Low Forward Voltage (V_F) Minimizes Conduction Losses and Improves Efficiency
- Reduced High Temperature Reverse Leakage; Increased Reliability Against Thermal Runaway Failure in High-Temperature Operation
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Description and Applications

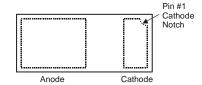
The SDM2A40CSP is a 40V 2A Schottky barrier rectifier optimized for low forward voltage drop and low leakage current housed in a compact chip scale package (CSP) that occupies only 1.28mm² board space with a low profile. The low thermal resistance enables designers to meet design challenges of increasing efficiency while at the same time reducing board space. It is ideally suited for use in portable applications as a:

- Blocking Diode
- Boost Diode
- Switching Diode
- Reverse Protection Diode

Mechanical Data

- Case: X3-WLB1608-2
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiAu Bump. Solderable per MIL-STD-202, Method 208 @4)
- Polarity: Cathode Dot
- Weight: 0.001 grams (Approximate)





Ordering Information (Note 4)

| Part Number | Case | Packaging | | |
|---------------|--------------|--------------------|--|--|
| SDM2A40CSP-7B | X3-WLB1608-2 | 10,000/Tape & Reel | | |

Notes:

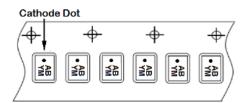
- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information





XB= Product Type Marking Code YM=Date Code Marking Y or Y= Year (ex: F = 2018) M=Month (ex: 9= September) Dot Denotes Cathode Pin



Date Code Key

| Date Code Itey | | | | | | | | | | | | |
|----------------|------|------|-------|-----|-------|------|-----|------|-----|------|------|------|
| Year | 201 | 8 | 2019 | | 2020 | 20 | 21 | 2022 | | 2023 | - 2 | 2024 |
| Code | F | | G | | Н | | I | J | | K | | L |
| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
| WOITE | Vali | 1 60 | IVICI | Αþi | iviay | ouii | oui | Aug | ОСР | OCI | 1404 | Dec |
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 0 | N | D |



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

| Charac | teristic | Symbol | Value | Unit |
|--|--|------------------|--------|------|
| Peak Repetitive Reverse Voltage | | V_{RRM} | 40 | V |
| Average Rectified Output Current | | lo | 2 | Α |
| Non-Repetitive Peak Forward Surg Single Half Sine-Wave Superimpos | | I _{FSM} | 28 | А |
| Repetitive Peak Forward Current (Pulse Wave = 1 sec, Duty Cycle = | 66%) | I _{FRM} | 4 | А |
| ESD Rating | Human Body Model Charged Device Model | ESD | 8 1 | KV |

Thermal Characteristics

| Characteristic | Symbol | Value | Unit |
|---|-----------------------------------|-------------|------|
| Typical Thermal Resistance Junction to Ambient (Note 5) | R _{OJA} | 137 | °C/W |
| Total Power Dissipation (Note 5) | P _{TOT} | 900 | mW |
| Typical Thermal Resistance Junction to Ambient (Note 6) | R _Ð JA | 50 | °C/W |
| Total Power Dissipation (Note 6) | Ртот | 2 | W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55 to +150 | °C |

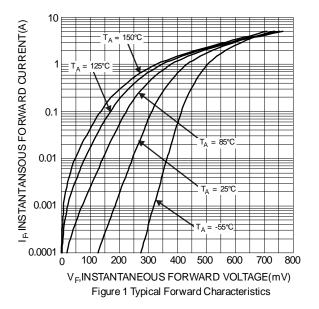
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

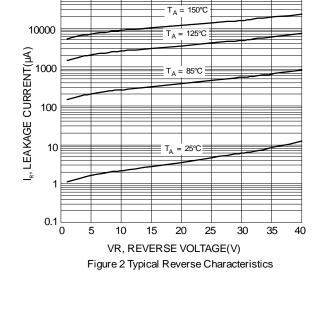
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition |
|--------------------------|----------------|-----|----------------|-------------------|------|--|
| Forward Voltage Dren | M | | 0.43 | 0.47 | V | I _F = 1.0A, T _J = +25°C |
| Forward Voltage Drop | V_{F} | 1 | 0.52 | 0.58 | V | I _F = 2.0A, T _J = +25°C |
| Reverse Current (Note 7) | I _R | | 2 13 600 | 18 100 2000 | μΑ | V _R = 10V, T _J = +25°C V _R = 40V, T _J = +25°C V _R = 32V, T _J = +85°C |
| Junction Capacitance | Ст | _ | 81 | _ | pF | V _R = 5V, f = 1.0MHz |
| Reverse Recovery Time | trr | | 14 | _ | ns | I _F =0.5A, I _R =1.0A, I _{rr} =0.25A |

Notes:

- 5. Device mounted on FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com/package-outlines.html. 6. Device mounted on FR-4 PCB, 1 inch sq. copper pad, 2oz.
- 7. Short duration pulse test used to minimize self-heating effect.







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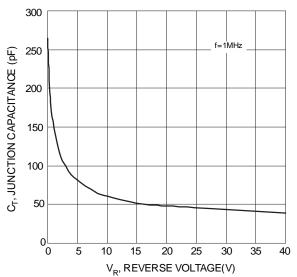


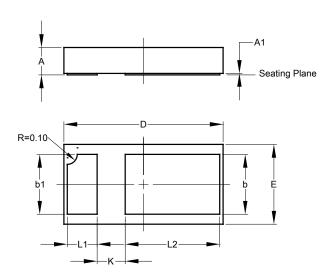
Figure 3 Typical Junction Capacitance



Package Outline Dimensions (Note 8)

Please see http://www.diodes.com/package-outlines.html for the latest version.

X3-WLB1608-2



| X3-WLB1608-2 | | | | | | | |
|--------------|----------------------|-------|-------|--|--|--|--|
| Dim | Min | Max | Тур | | | | |
| Α | 0.250 | 0.300 | 0.275 | | | | |
| A1 | _ | 0.015 | _ | | | | |
| b | | _ | 0.600 | | | | |
| b1 | | | 0.600 | | | | |
| D | 1.57 | 1.63 | 1.60 | | | | |
| E | 0.77 | 0.83 | 0.80 | | | | |
| K | _ | _ | 0.282 | | | | |
| L1 | 0.25 | 0.35 | 0.30 | | | | |
| L2 | 0.90 | 1.00 | 0.95 | | | | |
| All I | All Dimensions in mm | | | | | | |

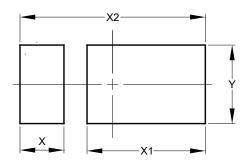
Note:

8. Device side walls are electrically active bare silicon. Avoid contact of solder or flux on the side walls during the PCB assembly process.

Suggested Pad Layout

 $\label{lem:please} Please see \ http://www.diodes.com/package-outlines.html \ for \ the \ latest \ version.$

X3-WLB1608-2



| Dimensions | Value (in mm) |
|------------|------------------|
| Х | 0.385 |
| X1 | 1.035 |
| X2 | 1.622 |
| Υ | 0.690 |



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